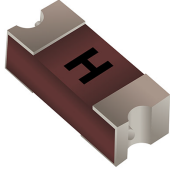


# MATERIAL DECLARATION SHEET



Material Number	SF-2410SPxxxW			
Product Line	Lead Free Time Lag Wire Core Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Body	Epoxy Board	38.197	Carbon	7440-44-0	41.25%	30.26%	73.36%
				Oxygen	7782-44-7	36.15%	26.52%	
				Silicon	7440-21-3	18.23%	13.37%	
				Hydrogen	1333-74-0	3.75%	2.75%	
				Aluminum	7429-90-5	0.26%	0.19%	
				Calcium	7440-70-2	0.36%	0.26%	
2	Fuse Link	Copper Composite Wire	0.1778	Alloy	Trade secret	68.03%	0.24%	0.34%
				Copper	7440-50-8	31.97%	0.10%	
3	Copper Layer (Termination)	Copper	11.15	Copper	7440-50-8	100.00%	21.41%	21.41%
4	Nickel Layer (Termination)	Nickel	1.632	Nickel	7440-02-0	100.00%	3.13%	3.14%
5	Tin Layer (Termination)	Tin	0.816	Tin	7440-31-5	100.00%	1.57%	1.57%
				Carbon	7440-44-0	34.81%	0.063%	
				Oxygen	7782-44-7	28.34%	0.051%	

# MATERIAL DECLARATION SHEET



				Barium	7440-39-3	23.29%	0.042%	
				Hydrogen	1333-74-0	3.03%	0.005%	
				Silicon	7440-21-3	4.03%	0.0073%	
				Magnesium	7439-95-4	1.02%	0.0018%	
				Sulfur	7704-34-9	5.44%	0.0098%	
				Nitrogen	7727-37-9	0.07%	0.00012%	
			Total weight	52.067				

**This Document was updated on: 8-30-17**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.